

Cell K Y Wong

List of Publications by Year in descending order

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11
papers

175
citations

1684188

5
h-index

2053705

5
g-index

11
all docs

11
docs citations

11
times ranked

221
citing authors

#	ARTICLE	IF	CITATIONS
1	Functionalization-induced changes in the structural and physical properties of amorphous polyaniline: a first-principles and molecular dynamics study. Scientific Reports, 2016, 6, 20621.	3.3	40
2	Molecular modeling of temperature dependence of solubility parameters for amorphous polymers. Journal of Molecular Modeling, 2012, 18, 2333-2341.	1.8	67
3	Synergistic Toughening of Epoxy-Copper Interface Using a Thiol-Based Coupling Layer. Journal of Adhesion Science and Technology, 2011, 25, 2081-2099.	2.6	5
4	Thiol-based self-assembly nanostructures in promoting interfacial adhesion for copper-epoxy joint. Applied Physics Letters, 2009, 94, .	3.3	19
5	Hydrophobic self assembly molecular layer for reliable Cu-epoxy interface. , 2009, , .		4
6	A multiscale method to predict delamination in Cu-epoxy systems in electronic packages. , 2009, , .		6
7	Hydrophobic self-assembly monolayer structure for reduction of interfacial moisture diffusion. , 2009, , .		4
8	Thiol based chemical treatment as adhesion promoter for Cu-epoxy interface. , 2008, , .		6
9	Interfacial Adhesion Study for SAM Induced Covalent Bonded Copper-EMC Interface by Molecular Dynamics Simulation. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 297-308.	1.3	24
10	Kinetics Study of Disulfide Self Assembly Monolayer (SAM) Deposition for Cu-EMC Adhesion Promotion. , 2006, , .		0
11	Kinetic Study of Disulfide Molecular Film Deposition for Cu-EMC Adhesion Promotion. Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International, 2006, , .	0.0	0